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(12) United States Design Patent

Podubni

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(54) **MODULER CIRCUIT BOARD**

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(73) Assignee: **TinyPCB, Inc.**

(**) Term: **15 Years**

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(51) **LOC (11) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

(58) **Field of Classification Search**
USPC D13/182; 174/68.1, 250, 253, 255, 256; 318/567, 568.1; 361/600, 601, 718, 719, 361/720, 728, 736, 748, 751, 752, 760, 361/761, 807; 439/55, 65, 68, 76.1, 92, 439/93, 95
CPC H05K 3/00; H05K 3/30; H05K 3/301; H05K 3/303; H05K 3/34; H05K 3/3405; H05K 3/341; H05K 3/36; H05K 3/361; H05K 3/363; H05K 3/40; H05K 7/14; H05K 7/1422; H05K 7/00; H05K 1/18; H05K 1/02; H05K 1/181; H05K 1/182; H05K 1/183; H05K 1/184; H05K 1/189; H05K 1/00
See application file for complete search history.

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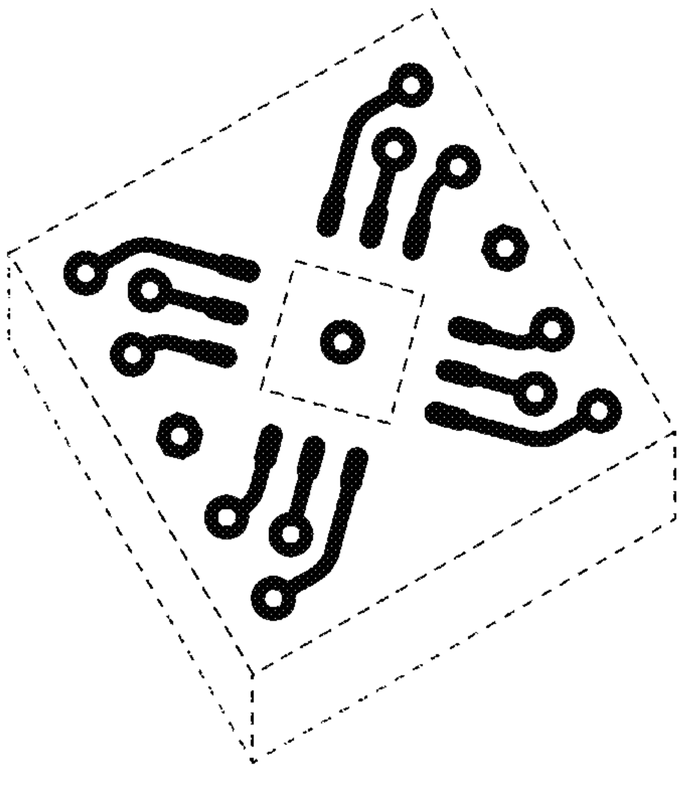
(57) **CLAIM**

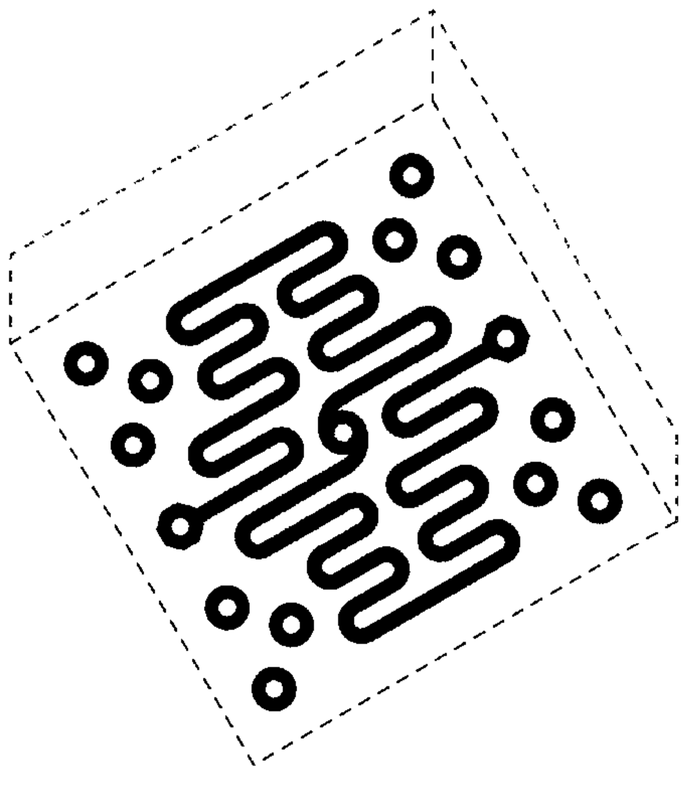
The ornamental design for a modular circuit board, as shown and described.

DESCRIPTION

FIG. **1** is a top perspective view of a modular circuit board, showing my new design;
FIG. **2** is a bottom perspective view thereof;
FIG. **3** is a top view thereof;
FIG. **4** is a bottom view thereof; and,
FIG. **5** is a side view thereof, all other side views being a mirror image thereof.
The broken lines shown in the drawings represent portions of the modular circuit board that form no part of the claimed design.

1 Claim, 5 Drawing Sheets





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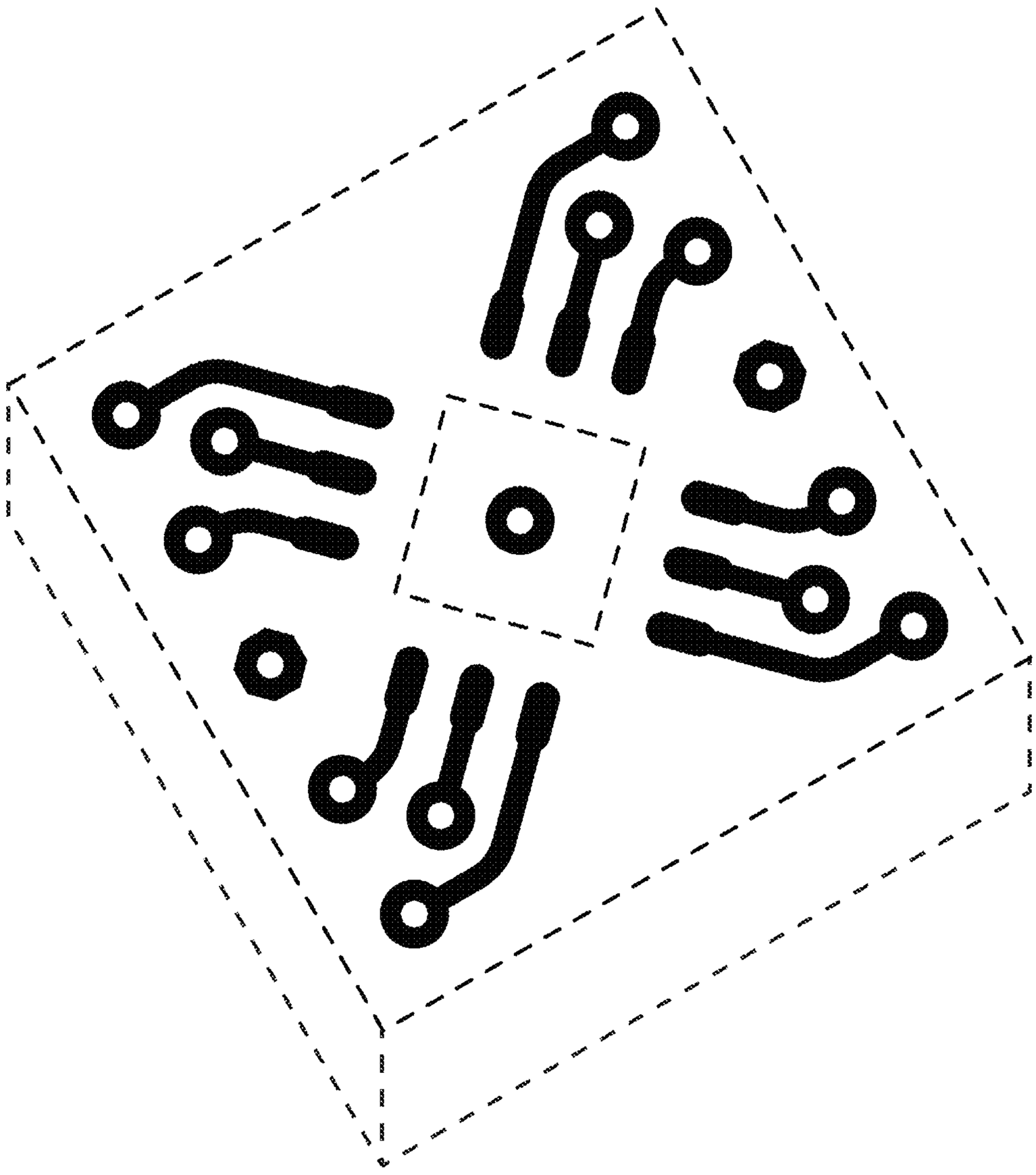

FIG. 1

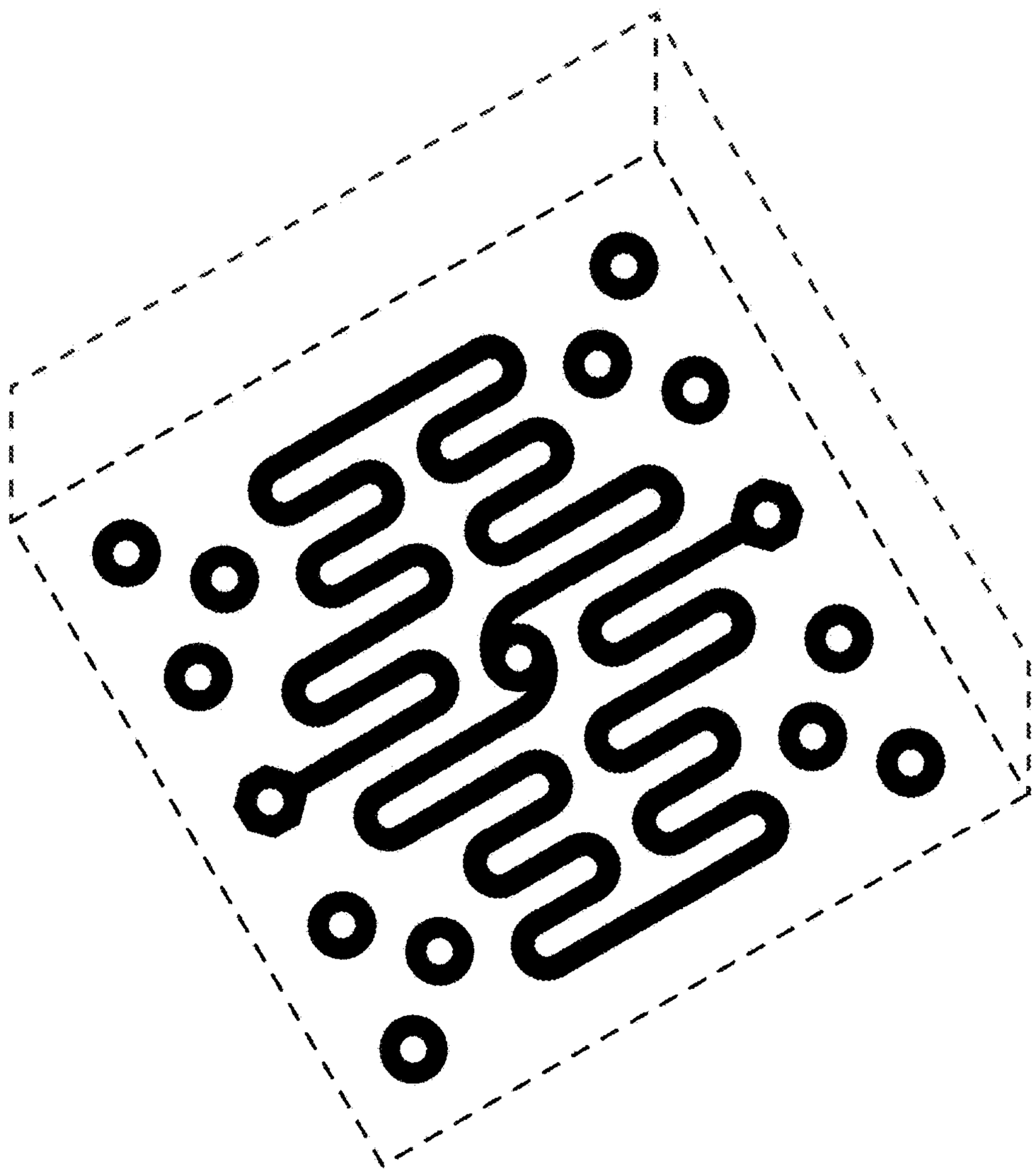

FIG. 2

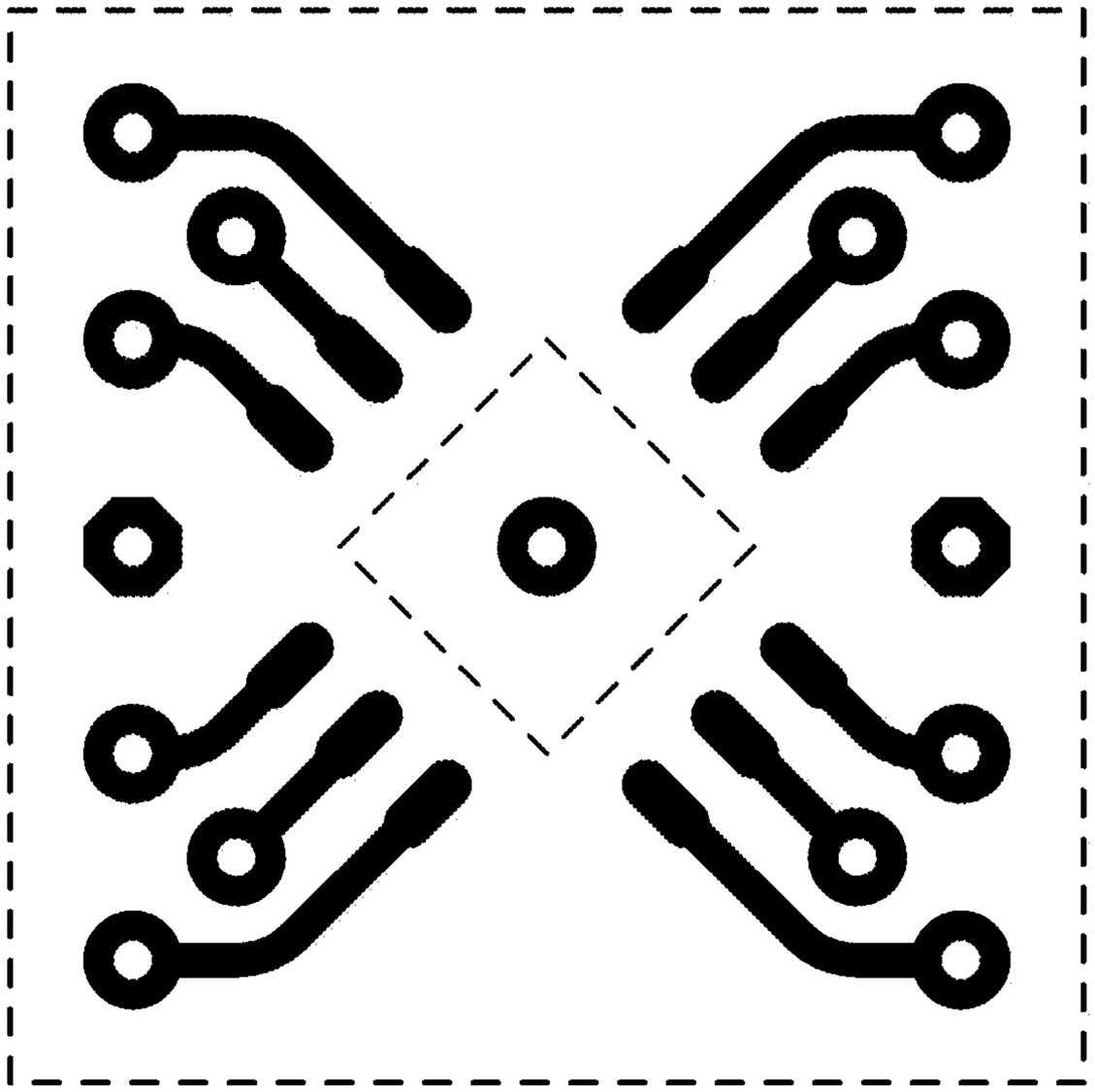

FIG. 3

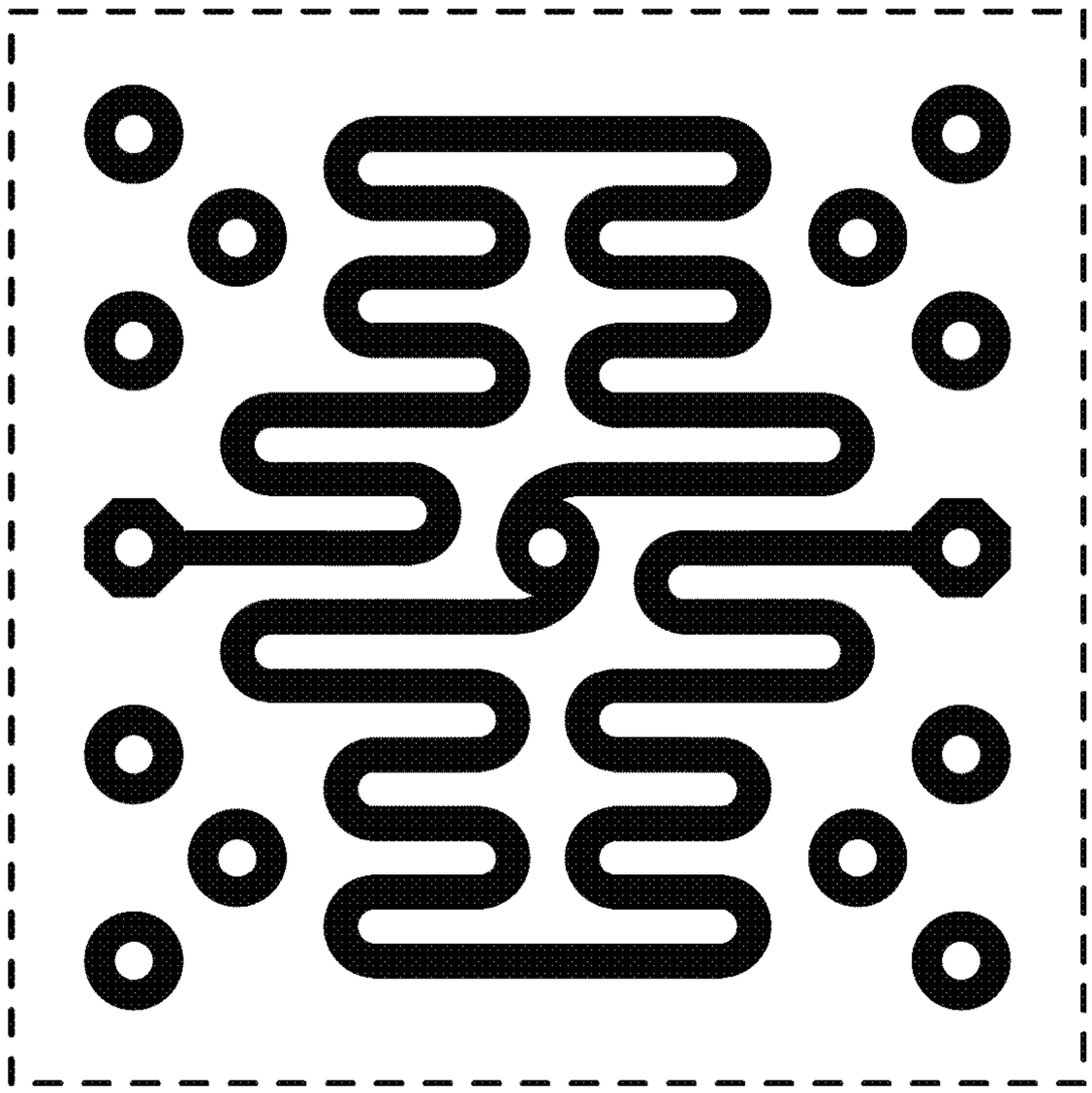

FIG. 4

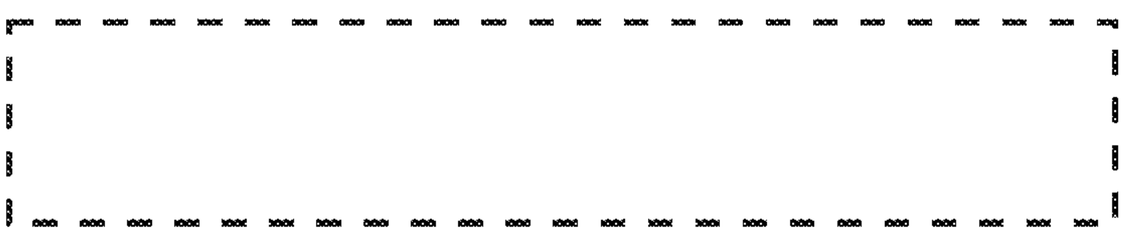

FIG. 5